

## Overview of index of products and services

<b>1</b>	<b>Materials</b>	<b>4</b>	<b>Inspection and test systems</b>
<b>2</b>	<b>Manufacturing processes</b>	<b>5</b>	<b>Devices</b>
<b>3</b>	<b>Electronics assembly and packaging, system integration</b>	<b>6</b>	<b>Applications</b>
		<b>7</b>	<b>Services</b>

## Index of products and services

- |                                |   |                                 |                                       |
|--------------------------------|---|---------------------------------|---------------------------------------|
| <b>1</b>                       | <b>Materials</b>                              | 2.2                             | Digital printing                      |
| 1.1                            | Substrates                                    | <input type="checkbox"/> 2.2.1  | Ink-jet printing                      |
| <input type="checkbox"/> 1.1.1 | Plastic films                                 | <input type="checkbox"/> 2.2.2  | Other digital printing                |
| <input type="checkbox"/> 1.1.2 | Metal foils                                   | 2.3                             | Other printing processes              |
| <input type="checkbox"/> 1.1.3 | Paper   | <input type="checkbox"/> 2.3.1  | Microcontact printing                 |
| <input type="checkbox"/> 1.1.4 | Glass   | <input type="checkbox"/> 2.3.2  | Nano imprint                          |
| <input type="checkbox"/> 1.1.5 | Textiles                                      | 2.4                             | Vacuum processes                      |
| <input type="checkbox"/> 1.1.6 | Other substrates                              | <input type="checkbox"/> 2.4.1  | Evaporation                           |
| 1.2                            | Conductors                                    | <input type="checkbox"/> 2.4.2  | Sputtering                            |
| <input type="checkbox"/> 1.2.1 | Organic conductors                            | <input type="checkbox"/> 2.4.3  | Organic vapor phase deposition (OVPD) |
| <input type="checkbox"/> 1.2.2 | Inorganic conductors                          | <input type="checkbox"/> 2.4.4  | Other vacuum processes                |
| <input type="checkbox"/> 1.2.3 | Nano materials                                | <input type="checkbox"/> 2.5    | Photolithography                      |
| <input type="checkbox"/> 1.2.4 | Carbon nanotubes                              | 2.6                             | Laser processes                       |
| <input type="checkbox"/> 1.2.5 | Graphene                                      | <input type="checkbox"/> 2.6.1  | Laser ablation                        |
| <input type="checkbox"/> 1.2.6 | Hybrid conductors                             | <input type="checkbox"/> 2.6.2  | Laser transfer                        |
| 1.3                            | Semiconductors                                | 2.7                             | Coating technologies                  |
| <input type="checkbox"/> 1.3.1 | Polymer semiconductors                        | <input type="checkbox"/> 2.7.1  | Spin coating                          |
| <input type="checkbox"/> 1.3.2 | Small molecule semiconductors                 | <input type="checkbox"/> 2.7.2  | Dip coating                           |
| <input type="checkbox"/> 1.3.3 | Inorganic semiconductors                      | <input type="checkbox"/> 2.7.3  | Blade coating                         |
| <input type="checkbox"/> 1.3.4 | Nano materials semiconductors                 | <input type="checkbox"/> 2.7.4  | Other coating techniques              |
| <input type="checkbox"/> 1.3.5 | Carbon nanotube semiconductors                | 2.8                             | Material processing                   |
| <input type="checkbox"/> 1.3.6 | Hybrid semiconductors                         | <input type="checkbox"/> 2.8.1  | Dispersion technologies               |
| 1.4                            | Dielectrics                                   | <input type="checkbox"/> 2.8.2  | Other material processing             |
| <input type="checkbox"/> 1.4.1 | Organic dielectrics                           | 2.9                             | Light induced processing              |
| <input type="checkbox"/> 1.4.2 | Inorganic dielectrics                         | <input type="checkbox"/> 2.9.1  | IR drying                             |
| <input type="checkbox"/> 1.4.3 | Nano materials                                | <input type="checkbox"/> 2.9.2  | UV curing                             |
| <input type="checkbox"/> 1.4.4 | Hybrid dielectrics                            | <input type="checkbox"/> 2.9.3  | Laser processes                       |
| 1.5                            | Encapsulation materials, resins and adhesives | 2.10                            | Dosing and mixing technology          |
| <input type="checkbox"/> 1.5.1 | Thin film encapsulation                       | <input type="checkbox"/> 2.10.1 | Pumps                                 |
| <input type="checkbox"/> 1.5.2 | Polymer film encapsulation                    | <input type="checkbox"/> 2.10.2 | Other dosing and mixing technologies  |
| <input type="checkbox"/> 1.5.3 | Metal encapsulation                           | 2.11                            | Encapsulation                         |
| <input type="checkbox"/> 1.5.4 | Glass encapsulation                           | <input type="checkbox"/> 2.11.1 | Thin film encapsulation               |
| <input type="checkbox"/> 1.5.5 | Resins and adhesives                          | <input type="checkbox"/> 2.11.2 | Polymer film encapsulation            |
| <input type="checkbox"/> 1.6   | Other materials                               | <input type="checkbox"/> 2.11.3 | Metal encapsulation                   |
|                                |   | <input type="checkbox"/> 2.11.4 | Glass encapsulation                   |
|                                |   | <input type="checkbox"/> 2.11.5 | Other encapsulation processes         |
| <b>2</b>                       | <b>Manufacturing processes</b>                | <input type="checkbox"/> 2.12   | Clean room technology                 |
| 2.1                            | Mass patterning techniques                    | <input type="checkbox"/> 2.13   | Roll-to-roll processing               |
| <input type="checkbox"/> 2.1.1 | Gravure printing                              | <input type="checkbox"/> 2.14   | Other manufacturing processes         |
| <input type="checkbox"/> 2.1.2 | Offset printing                               |                                 |                                       |
| <input type="checkbox"/> 2.1.3 | Flexographic printing                         |                                 |                                       |
| <input type="checkbox"/> 2.1.4 | Screen printing                               |                                 |                                       |
| <input type="checkbox"/> 2.1.5 | Other mass patterning techniques              |                                 |                                       |

# Index of products and services

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## 3 Electronics assembly and packaging, system integration

- 3.1 Electronics assembly and packaging
  - 3.1.1 Flip chip
  - 3.1.2 Other electrical contacting
- 3.2 Lamination
- 3.3 System integration
- 3.4 Hybrid systems (polytronics)

## 4 Inspection and test systems

- 4.1 Electrical characterization
- 4.2 Physical/optical characterization
- 4.3 Chemical characterization
- 4.4 Simulation/circuit optimization
- 4.5 Lifetime testing
- 4.6 Quality/process control
- 4.7 Environmental testing
- 4.8 Other inspection and test systems

## 5 Devices

- 5.1 Transistors
- 5.2 Diodes
- 5.3 Passive components
  - 5.3.1 Capacitors
  - 5.3.2 Resistors
  - 5.3.3 Other passives
- 5.4 Integrated circuits
- 5.5 Displays
  - 5.5.1 OLED
  - 5.5.2 Electrochromic displays
  - 5.5.3 Electrochromic displays
  - 5.5.4 Electroluminescent displays
  - 5.5.5 LCD
  - 5.5.6 Electrowetting
  - 5.5.7 Other displays
- 5.6 Photovoltaic cells
  - 5.6.1 Organic photovoltaics
  - 5.6.2 Hybrid photovoltaics
  - 5.6.3 Inorganic photovoltaics

## 5.7 Sensors

- 5.7.1 Photodiodes
- 5.7.2 Pressure sensors
- 5.7.3 Temperature sensors
- 5.7.4 Biomedical sensors
- 5.7.5 Gas sensors
- 5.7.6 Touch sensors
- 5.7.7 Other sensors
- 5.8 Memory elements
- 5.9 Antennas
- 5.10 Batteries
- 5.11 Components for hybrid systems
- 5.12 Other devices

## 6 Applications

- 6.1 TFT backplanes
- 6.2 Displays
- 6.3 Sensors
- 6.4 Smart systems
- 6.5 RFID
- 6.6 Solar cells
- 6.7 Smart textiles
- 6.8 Speakers
- 6.9 Lighting
- 6.10 Other applications

## 7 Services

- 7.1 Consulting
- 7.2 R&D funding program management
- 7.3 R&D/Research & Development
- 7.4 Prototyping
- 7.5 Manufacturing
- 7.6 Venture and equity capitalization
- 7.7 Professional and trade associations
- 7.8 Technical books, technical journals, technical publishers
- 7.9 Other services